

Docket No.: P2000,0171



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Date: October 9, 2001

8-23-02  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Bruno Acklin et al.  
Applic. No. : 09/932,878  
Filed : August 20, 2001  
Title : Method for Producing Semiconductor Laser Component

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INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,  
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

German Patent DE 196 44 941 C1 (Dohle et al.), dated January 15, 1998, high-power diode laser and method for mounting it;

German Published, Non-Prosecuted Patent Application DE 40 17 698 A1 (Seipler), dated December 5, 1991, method for building sensors using thick film technology;

German Published, Non-Prosecuted Patent Application DE 43 19 944 A1 (Schulz-Harder), dated December 8, 1994, multiple substrate as well as method for producing it;

German Published, Non-Prosecuted Patent Application DE 198 21 544 A1 (Lorenzen et al.), dated December 16, 1999, diode laser component and method for producing it;

German Published, Non-Prosecuted Patent Application DE 198 27 414 A1 (Schulz-Harder), dated December 23, 1999, method for producing a metal ceramic substrate;

L. J. Missaggia et al.: "Microchannel Heat Sinks for Two-Dimensional High-Power-Density Diode Laser Arrays", IEEE Journal of Quantum Electronics, Vol. 25, No. 9, September 1989, pp. 1988-1992;

Data sheet for laser diode SPL CGxx, xx=81, 94 or 98, Osram Opto Semiconductors, January 1, 2000.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,

  
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For Applicants

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Date: October 9, 2001

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FORM PTO-1449 (SUBSTITUTE) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE  INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))				Attorney Docket No.: P2000,0171  Applicant Bruno Acklin et al.  Filing Date August 20, 2001				Applic. No. 09/932,878  Group Art Unit 0.0	
U.S. PATENT DOCUMENTS									
EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE		
	A								
	B								
	C								
	D								
	E								
	F								
	G								
	H								
	I								
FOREIGN PATENT DOCUMENT									
		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES   NO		
	J	196 44 941 C1	01/15/98	Germany				X	
	K	40 17 698 A1	12/05/91	Germany				X	
	L	43 19 944 A1	12/08/94	Germany				X	
	M	198 21 544 A1	12/16/99	Germany				X	
	N	198 27 414 A1	12/23/99	Germany				X	
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)									
	O	L. J. Missaggia et al.: "Microchannel Heat Sinks for Two-Dimensional High-Power-Density Diode Laser Arrays", IEEE Journal of Quantum Electronics, Vol. 25, No. 9, September 1989, pp. 1988-1992							
	P	Data sheet for laser diode SPL CGxx, xx=81, 94 or 98, Osram Opto Semiconductors, January 1, 2000							
EXAMINER				DATE CONSIDERED					
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									